KMY

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Specification

(Reference)

Title: CHIP FUSE; RECTANGULAR TYPE

Style: FMC10, 16

RoHS COMPLIANCE ITEM

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Issue Dept.: Research & Development Department Hokkaido Research Center

Drawing No: FMC-K-HTS-0001

CHIP FUSES; RECTANGULAR TYPE

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1. Scope

1.1 This specification covers the detail requirements for chip fuses; rectangular type, style of FMC10, 16.

1.2 Applicable documents

UL248-1-2000 Low-Voltage Fuses-Part1: General Requirements

UL248-14-2000 Low-Voltage Fuses-Part14: Supplemental Fuses

CSA C22.2 No.248.1–2000 Low-Voltage Fuses-Part1: General Requirements

CSA C22.2 No.248.14-2000 Low-Voltage Fuses-Part14: Supplemental Fuses

2. Classification

Type designation shall be the following form.

(Example) FMC 16 202 AB TP

1 2 3 4 5

1 Chip fuses; rectangular type
2 Size Style

3 Rated current Example:
$$202 \rightarrow 2.0$$
 (A)

4 Optional code

5 Packaging form

3. Safety standard approval

- UL248-1 and UL248-14
- CSA C22.2, No. 248.1–00 and CSA C22.2, No. 248.14–00

The file number to be designated by UL and C-UL shall be as follows: E176847

4. Rating

The ratings shall be in accordance with Table-1.

4.1 Optional code: AB

Toble 4/4)

| | | | | 1able-1(1) | | | | |
|-----------|---------------|------|---------------------------|-------------------|----------------|-------------------------------|---------|----------------------|
| | Rated current | | Internal resistance value | Rated | Breaking | Time / current characteristic | | |
| Style | Symbol | (A) | Marking symbol | $(m\Omega \max.)$ | voltage (V) | capacity (A) | Current | Pre-arcing time |
| | 501 0.5 F 240 | | | | | | | |
| | 751 | 0.75 | Α | 140 | DC24 | 35 | | |
| | 102 | 1.0 | L | 95 | | | | 4 h min. 5 s max. |
| FMC10 | 132 | 1.25 | М | 73 | | | | |
| I IVIC IO | 152 | 1.5 | Н | 60 | DC24 | 33 | 300% | 0.2 s max. |
| | 202 | 2.0 | S | 41 | | | 00070 | 0.2 3 max. |
| | 252 | 2.5 | Т | 32 | | | | |
| | 302 | 3.0 | R | 25 | | | | |

Symbol Optional code AB **WB** Standard WH

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4.2 Optional code: WB

Table-1(2)

| | F | Rated current | | Internal resistance value | Rated | Breaking | Time / current characteristic | |
|---------|--------|---------------|-------------------|---------------------------|----------------|------------------------|-------------------------------|-----------------|
| Style | Symbol | (A) | Marking symbol | $(m\Omega \max.)$ | voltage (V) | capacity (A) | Current | Pre-arcing time |
| | 501 | 0.5 | F | 260 | 260 | | | |
| | 751 | 1 0.75 A 140 | | | | | | |
| | 102 | 1.0 | L | 110 | DC32 35 | | | |
| | 132 | 1.25 | М | 80 | | | 1000/ | 4 h min. |
| FMC16 | 152 | 1.5 | Н | 65 | | 25 | 100% 200% | |
| FIVICIO | 202 | 2 2.0 S 45 | DC32 | 33 | 300% | 5 s max. 0.2 s max. | | |
| | 252 | 2.5 | Т | 32 |] | | 30070 | 0.2 3 Hax. |
| | 302 | 3.0 | R | 26 | | | | |
| | 402 | 4.0 | Χ | 18 | | | | |
| | 502 | 5.0 | Υ | 14 | | | | |

4.3 Optional code: WH

Table-1(3)

| | F | Rated curre | ent | Internal resistance value | Rated | Breaking | Time / curr | ent characteristic |
|----------|---|-------------|-----------------|---------------------------|-----------------|----------|----------------------|------------------------------------|
| Style | tyle Symbol (A) Marking symbol $(m\Omega \text{ max.})$ voltage (V) | | capacity (A) | Current | Pre-arcing time | | | |
| | 501 | 0.5 | OF | 400 | | | | |
| | 631 | 0.63 | OI | 300 | | | | |
| | 751 | 0.75 | OA | 210 | | | | |
| | 801 | 0.8 | OK | 180 | DC32 35 | | | |
| | 102 | 1.0 | OL | 115 | | | | |
| | 132 | 1.25 | OM | 90 | | | 100% 200% 300% | 4 h min. 5 s max. 0.2 s max. |
| FMC16 | 152 | 1.5 | ОН | 70 | | 25 | | |
| FIVIC 16 | 162 | 1.6 | ON | 60 | | 33 | | |
| | 202 | 2.0 | OS | 50 | | | 30070 0.2 | 0.2 3 max. |
| | 252 | 2.5 | OT | 37 | | | | |
| | 302 | 3.0 | OR | 28 | | | | |
| | 322 | 3.15 | OU | 26 | | | | |
| | 402 | 4.0 | OX | 18 | | | | |
| | 502 | 5.0 | OY | 14 | | | | |

^{4.4} Working temperature range: -55 to +125(°C)

5. Packaging form

The standard packaging form shall be in accordance with Table-2.

Table-2

| Symbol | Packaning inm | | Packaning into | | Standard packaging quantity / units | Application |
|--------|----------------------|------------------------|----------------|-----------|-------------------------------------|-------------|
| В | Bulk (loose package) | | 1,000 pcs. | FMC10, 16 | | |
| TH | Paper taping | 8mm width, 2mm pitches | 10,000 pcs. | FMC10 | | |
| TP | Paper taping | 8mm width, 4mm pitches | 5,000 pcs. | FMC16 | | |

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6. Dimensions

6.1 The resistor shall be of the design and physical dimensions in accordance with Figure-1 and Table-3.

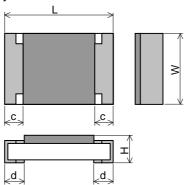


Figure-1 Table-3

 Table–3
 Unit : mm

 L
 W
 H
 c
 d

 1.0±0.05
 0.5±0.05
 0.38±0.05
 0.2±0.10
 0.25±0.10

 1.6±0.1
 0.8 ±0.15
 0.45±0.10
 0.3±0.15
 0.3±0.1

6.2 Net weight (Reference)

| Style | Net weight(mg) |
|-------|----------------|
| FMC10 | 0.6 |
| FMC16 | 2 |

Style

FMC10

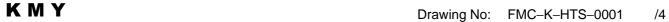
FMC16

7. Marking

The Marking symbol of Sub-clause 4.1 shall be marked on over coat side.

(Example)

| Style | Optional code | Marking symbol | Content |
|-------|---------------|----------------|--------------|
| FMC10 | AB | S | FMC10 202 AB |
| FMC16 | WB | S | FMC16 202 WB |
| FMC16 | WH | OS | FMC16 202 WH |



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8. Performance

8.1 Unless otherwise specified, the standard range of atmospheric conditions for tests is as follows;

Ambient temperature: 5 °C to 35 °C, Relative humidity: 45 % to 85 %, Air presser: 86 kPa to 106 kPa

If there is any doubt the results, measurements shall be made within the following:

Ambient temperature: 20 °C \pm 2 °C, Relative humidity: 60 % to 70 %, Air presser: 86 kPa to 106 kPa

8.2 The performance shall be satisfied in Table-4.

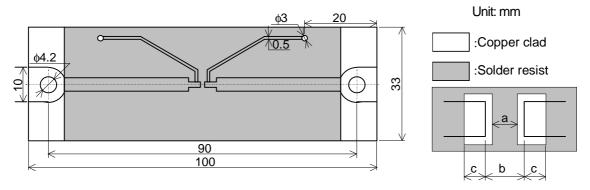
Table-4(1)

| No. | Test items | Condition of test | Perforr | mance requirements |
|-----|--|--|---|---|
| 1 | Temperature rise | The fuse shall be mounted on the test substrate as shown in Figure–2. Measurement temp.: 10 °C to 30 °C Test current: Rated current The temperature at the hottest point on the surface of the fuse shall be measured after temperature equilibrium has been attained. | | |
| 2 | Time / current characteristic | The fuse shall be mounted on the test substrate as shown in Figure–2. Test current shall be applied for continuously. | Current 100% 200% 300% | Pre-arcing time 4 h min. 5 s. max. 0.2 s max. |
| 3 | Terminal bond strength of the face plating | JIS C 60068-2-21 Ue1 The fuse shall be mounted on the test substrate as shown in Figure–2. Bending value: 3 mm(Among the fulcrums: 90 mm) Duration: 10 s ± 1 s | | internal resistance: |
| 4 | Resistance to soldering heat | Test by a piece. Temp. of solder bath: 260 °C ± 5 °C Immersion time: 10 s ± 1 s After immersion into solder, leaving the room temp. for 1h or more, and then measure the internal resistance. • Reflow soldering Pre—heating: 150 °C ~ 180 °C, 120 s max. Peak: 260 °C ± 5 °C, 10 s max. Reflow cycle: 2 times After immersion into solder, leaving the room temp. for 1h or more, and then measure the internal resistance. | Change of ±10% No evide damage | internal resistance: ence of appearance |
| 5 | Solderability | | shall be mi | e of terminal immersed n. of 95 % covered with ing of solder. |
| 6 | Rapid change temperature | JIS C 60068-2-14 Na The fuse shall be mounted on the test substrate as shown in Figure–2. Lower temperature: –55 °C Upper temperature: +125 °C Duration of exposure at each temperature: 30 min. Number of cycles: 5 cycles | Change of ±10% No evide damage | internal resistance: ence of appearance |

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9. Test substrate



| Style | а | b | С |
|-------|-----|-----|------|
| FMC10 | 0.3 | 0.6 | 0.65 |
| FMC16 | 0.6 | 1.0 | 0.5 |

Figure-2 FMC TEST SUBSTRATE

Remark 1). Material: Epoxide woven glass

Thickness: 1. 6mm Thickness of copper clad: 0. 035mm

10. Taping

10.1 Applicable documents JIS C 0806-3: 1999, EIAJ ET-7200B: 2003

10.2 Taping dimensions

10.2.1 Paper taping (8mm width, 2mm pitches)

Taping dimensions shall be in accordance with Figure-3 and Table-5.

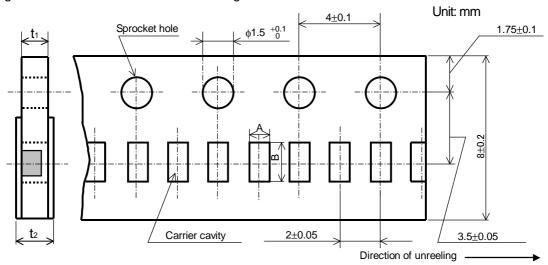


Figure-3

| | Unit: mm | | | |
|-------|------------|--|----------------|----------------|
| Style | Α | В | t 1 | t ₂ |
| FMC10 | 0.65 +0.05 | 1.15 ^{+0.05} _{-0.10} | 0.4 ± 0.05 | 0.5max. |

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10.2.2 Paper taping (8mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-4 and Table-6.

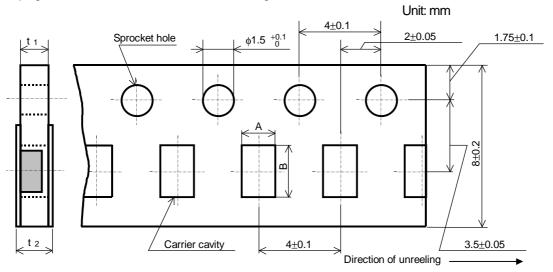


 Figure-4

 Table-6
 Unit : mm

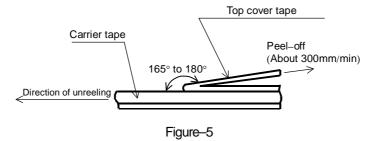
 Style
 A
 B
 t₁
 t₂

 FMC16
 1.15±0.15
 1.9±0.2
 0.6±0.1
 0.8 max.

- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following Figure–5.
- 6). When the tape is bent with the minimum radius for 25 mm, the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.

The maximum number of missing components shall be one or 0.1%, whichever is greater.

8). The fuses shall be faced to upward at the over coating side in the carrier cavity.



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10.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure-6 and Table-7.

Plastic reel (Based on EIAJ ET-7200B)

Unit: mm

A

B

Figure-6

Table-7

Linit: mm

| rigare e | | | | | | |
|---------------|----------------|----------|-------------------|--|--|--|
| | Unit: mm | | | | | |
| Style | Α | В | Note | | | |
| FMC10, 16 | C10, 16 9 +1.0 | 11.4±1.0 | Injection molding | | | |
| 1 1010 10, 10 | 9 0 | 13±1.0 | Vacuum forming | | | |

Note: Marking label shall be marked on a place of Marking A or two place of marking A and B.

10.4 Leader and trailer tape.

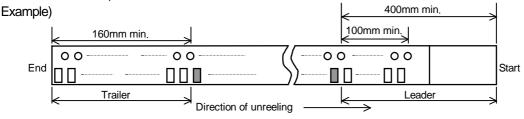


Figure-7

11. Marking on package

The label of a minimum package shall be legibly marked with follows.

11.1 Marking A

- (1) Classification (Style, Rated current, Optional code, Packaging form) (2) Quantity (3) Lot number
- (4) Manufacturer's name or trade mark (5) UL and /or C–UL recognized component mark (6) Others 11.2 Marking B (KAMAYA Control label)



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12. Recommended Derating for Rated Current

This fuse will recommend use by the current reduction value according to the following derating curve.

Nominal Derating

Nominal Derating ≤ 75% of Rated Current

Temperature Derating

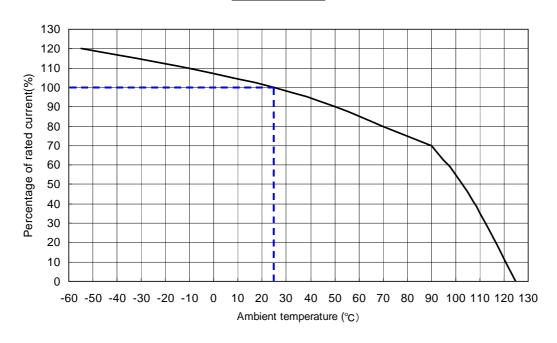
Please refer to the following graph regarding the current derating value for ambient temperature.

Ex.) If FMC16 202AH (Rated Current 2.0A) is used under ambient temperature 70°C,

Kamaya recommends, less than the current value derated as below,

Rated Current: 2.0A× (Nominal Derating: 75% × Temperature Derating: 80%) = 1.2A

Derating curve



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